

## **Product Information Sheet**

MATERIAL ID:	<b>EPO-TEK<sup>®</sup> 430</b>			
<b>Date:</b> 10/2006	Per:			
Rev: V				
Material Description:	A two component, copper-filled, electrically and thermally conductive epoxy for adhesive bonding in electronics. It may be used at the PCB level for inter- connecting, grounding and EMI RF shielding. Fast curing at relatively low temperatures may be realized.			
Number of Components:	Two			
Mix Ratio by weight:	100:2.5			
Cure Schedule (minimum)	80°C/30 Minutes - 60°C/1 Hour			
Specific Gravity:	Part A: 3.56 Part B: 1.02			
Pot Life:	3 Hours			
Shelf Life:	One year at room temperature - (viscosity will advance)			

*NOTE:* Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use

**MATERIAL CHARACTERISTICS:** *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour \* denotes test on lot acceptance basis* 

PHYSICAL PROPERTIES:					
*Color (before cure):	Part A: Brown Copper				
	Part B: Amber	Weight Loss:			
*Consistency:	Thick paste	@ 200°C:	0.18 %		
*Viscosity (23°C):		@ 250°C:	0.27 %		
@ 1.0 <b>rpm</b>	300,000 - 400,000 <b>cPs</b>	@ 300°C:	0.45 %		
Thixotropic Index:	N/A	<b>Operating Temp:</b>			
*Glass Transition Temp:	$\geq$ 110 ° <b>C</b> (Dynamic Cure	Continuous:	- $55^{\circ}$ C to + $250^{\circ}$ C		
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)		Intermittent:	- $55^{\circ}$ C to + $350^{\circ}$ C		
<b>Coefficient of Thermal Expansion (CTE):</b>		Storage Modulus @ 23°C:	608,362 <b>psi</b>		
Below Tg:	28 x 10 <sup>-6</sup> in/in°C	Ion Content:	· -		
Above Tg:	144 x 10 <sup>-6</sup> in/in°C	СГ:	33 ppm		
Shore D Hardness:	86	$NH_4^+$ :	63 <b>ppm</b>		
Lap Shear @ 23°C:	> 2,000 <b>psi</b>	Na <sup>+</sup> :	5 ppm		
Die Shear @ 23°C:	$\geq$ 5 Kg / 1,700 psi	<b>K</b> <sup>+</sup> :	> 1 <b>ppm</b>		
<b>Degradation Temp:</b>	420 °C	*Particle Size:	$\leq 50$ microns		

<b>ELECTRICAL AND THER</b>	MAL PROPERTIES:		
Thermal Conductivity:	1.34 <b>W/mK</b>	Dielectric Constant (1KHz):	N/A
*Volume Resistivity @ 23°C:	≤ 0.005 <b>Ohm-cm</b>	<b>Dissipation Factor</b> (1KHz):	N/A
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OPTICAL PROPERTIES @ 23°C:					
Spectral Transmission: N/A	Index of Refraction:	N/A			

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